

General Description

These N-Channel enhancement mode power field effect transistors are using SGT technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

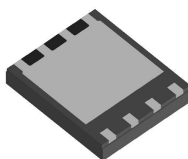
Features

V_{DS}	60V
I_D (at $V_{GS}=10V$)	220A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	1.35m Ω (Typ)

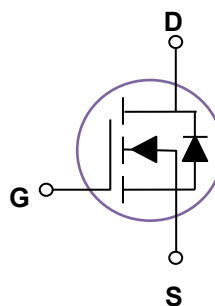
PDFN5*6



TOP VIEW



BOTTOM VIEW



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current-Continuous	$TC=25^\circ\text{C}$	I_D	220	A
	$TC=100^\circ\text{C}$	I_D	139	A
Drain Current – Pulsed		IDM	880	A
Maximum Power Dissipation		P_D	278	W
Single pulse avalanche energy ⁽¹⁾		E_{AS}	1300	mJ
Junction and Storage Temperature Range		T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		0.45	$^\circ\text{C} / \text{W}$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		62	$^\circ\text{C} / \text{W}$

Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V,V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V,V _{DS} =0V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250μA	2.0	2.8	4.0	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A		1.35	1.6	mΩ
gfs	Forward Transconductance	V _{DS} =10V , I _D =3A		30		S
DYNAMIC PARAMETERS						
C _{iSS}	Input Capacitance	V _{DS} =25V,V _{GS} =0V, F=1.0MHz		5800		pF
C _{oSS}	Output Capacitance			1200		pF
C _{rSS}	Reverse Transfer Capacitance			50		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DD} =30V,I _D =1A, V _{GS} =10V, R _G =6Ω		19		nS
t _r	Turn-on Rise Time			9		nS
t _{d(off)}	Turn-Off Delay Time			36		nS
t _f	Turn-Off Fall Time			10		nS
Q _g	Total Gate Charge	V _{DS} =50V,I _D =10A, V _{GS} =10V		71		nC
Q _{gs}	Gate-Source Charge			22		nC
Q _{gd}	Gate-Drain Charge			13		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V,I _{SD} =10A		0.72	1.4	V
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.0		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=30V, V_{GS}=10V, L=0.5mH, I_{AS}=90A.$, Starting TJ=25°C
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

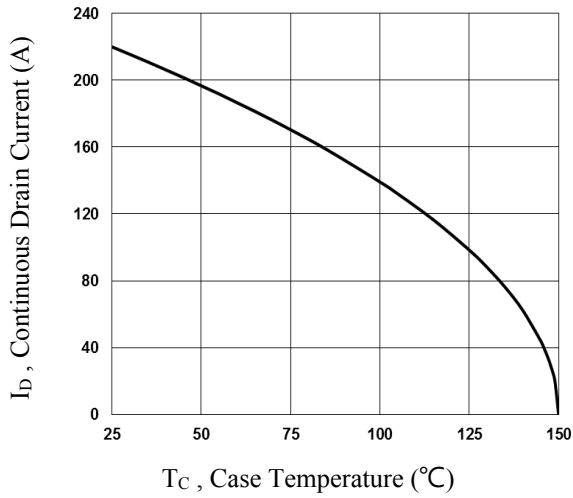


Fig.1 Continuous Drain Current vs. T_C

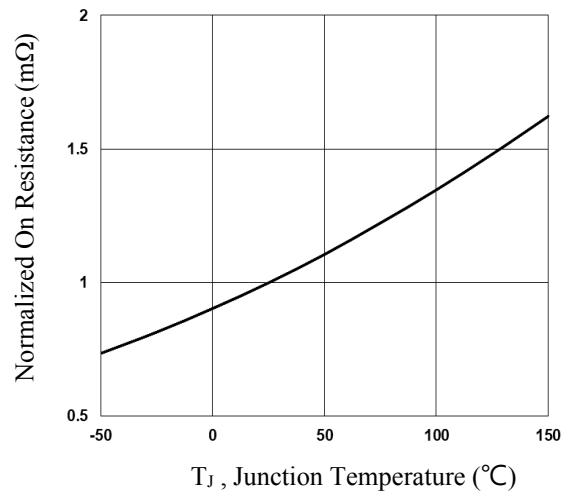


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

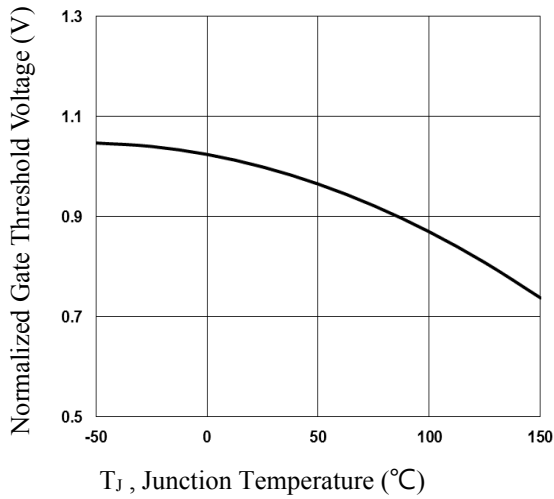


Fig.3 Normalized V_{th} vs. T_J

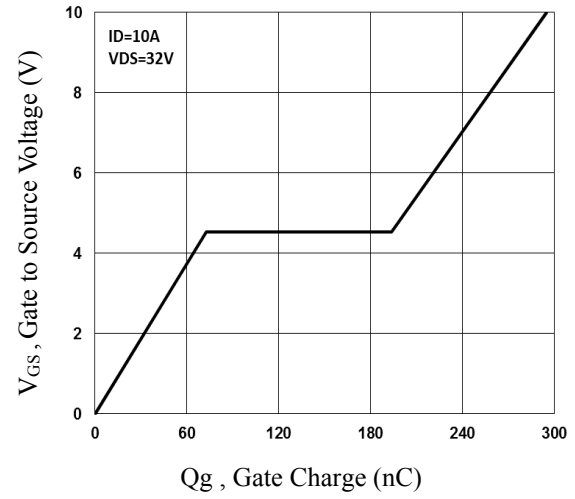


Fig.4 Gate Charge Characteristics

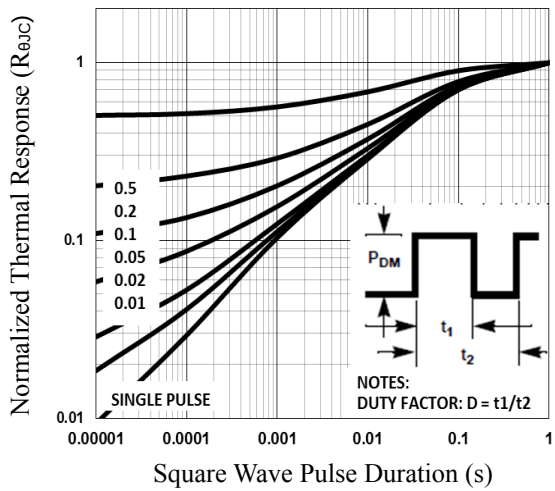


Fig.5 Normalized Transient Impedance

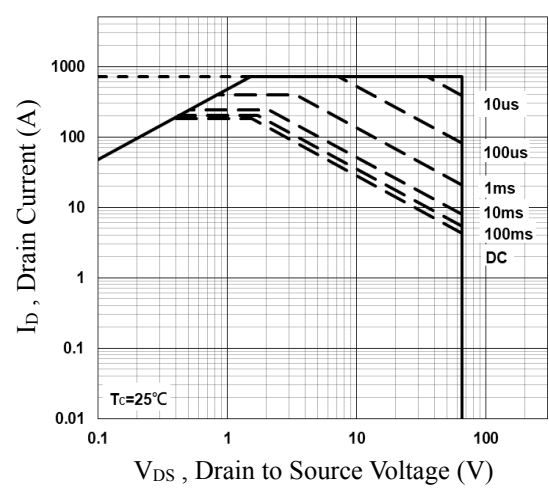


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

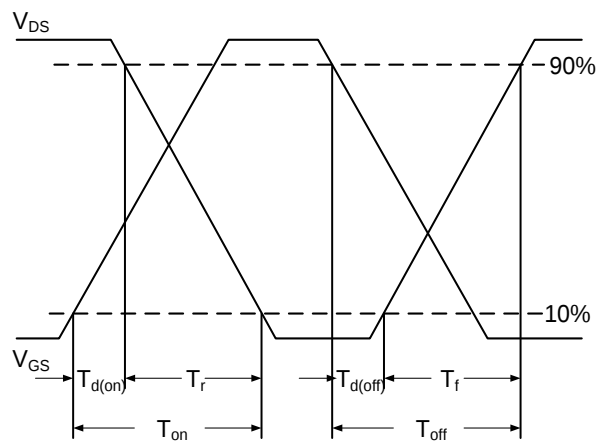


Fig.7 Switching Time Waveform

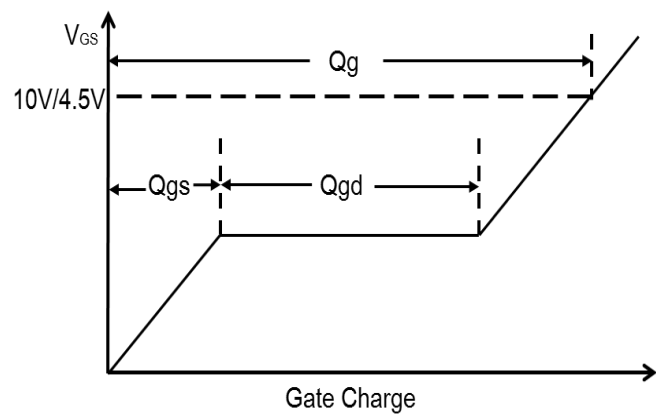
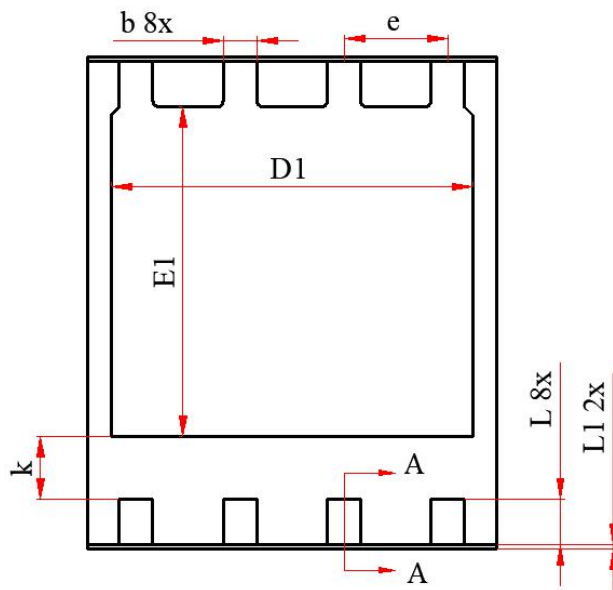
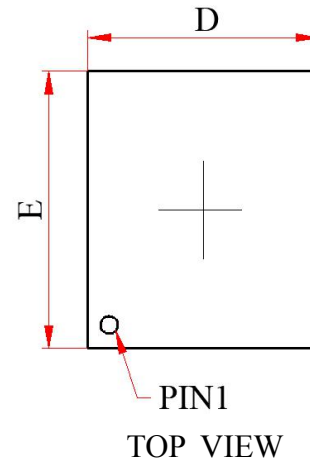


Fig.8 Gate Charge Waveform

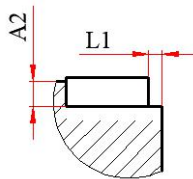
DFN5*6 PACKAGE INFORMATION



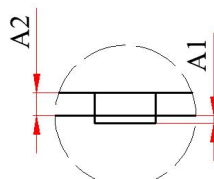
BOTTOM VIEW



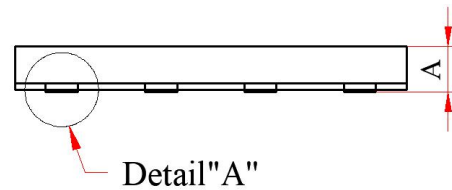
TOP VIEW



Section A-A



Detail "A"



SIDE VIEW

Symbol	Dimension In Millimeters			Dimension In Inches		
	Normal	Min	Max	Normal	Min	Max
A	--	0.500	0.600	--	0.020	0.024
A1	--	--	0.005	--	--	0.000
A2	--	0.100	0.250	--	0.004	0.010
D	5.000	4.900	5.100	0.197	0.193	0.201
E	6.000	5.900	6.100	0.236	0.232	0.240
D1	4.420	4.320	4.520	0.174	0.170	0.178
E1	4.020	3.920	4.120	0.158	0.154	0.162
b	0.410	0.360	0.460	0.016	0.014	0.018
L	0.560	0.510	0.610	0.022	0.020	0.024
L1	0.050	0.010	0.090	0.002	0.000	0.004
k	0.760 REF			0.030 REF		
e	1.270 BSC			0.050 BSC		